

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JIYE ZHAO	12/07/2021
DANDAN HUAN	12/07/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	BEIJING VCORE TECHNOLOGY CO.,LTD.
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<b>City:</b>	BEIJING
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	100082
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17708130
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<b>ATTORNEY DOCKET NUMBER:</b>	075559.10269
<b>NAME OF SUBMITTER:</b>	BLAIR K. ANDREWS
<b>SIGNATURE:</b>	/blair k andrews/
<b>DATE SIGNED:</b>	04/13/2022
<b>Total Attachments: 1</b>	
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ASSIGNMENT OF INVENTION

WHEREAS, We, **Jiye ZHAO**, Room 1105-2, Floor 10, Building 1, No. 66 Zhongguancun East Road, Haidian District, Beijing 100082, China; and **Dandan HUAN**, Room 1105-2, Floor 10, Building 1, No. 66 Zhongguancun East Road, Haidian District, Beijing 100082, China, have invented certain new and ornamental improvements in a **SEDRAM-BASED STACKED CACHE SYSTEM AND DEVICE AND CONTROLLING METHOD THEREFOR**, for which an application for Letters Patent in the United States is being filed, based upon International Application No. PCT/CN2021/096732 filed on May 28, 2021; claiming priority to Chinese Design Patent Application No. 202110214197.9 filed on February 26, 2021;

AND WHEREAS, **BEIJING VCORE TECHNOLOGY CO.,LTD.**, Room 1105-2, Floor 10, Building 1, No. 66 Zhongguancun East Road, Haidian District, Beijing 100190, China, is desirous of acquiring all interest in said invention, said application, and in any Letters Patent which may be granted therefor;

AND WHEREAS, at the time the invention was made, we were under an obligation to assign all of our right, title, and interest in said invention to **BEIJING VCORE TECHNOLOGY CO.,LTD.**

NOW THIS INDENTURE WITNESSETH, that for the sum of one dollar and other valuable consideration to us in hand paid, the receipt of which is hereby acknowledged, we hereby assign, sell, and transfer unto said **BEIJING VCORE TECHNOLOGY CO.,LTD.** our entire right, title, and interest in said invention, said application, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights, rights under the International Convention For The Protection Of Industrial Property, rights under the Patent Cooperation Treaty, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto.

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Letters Patent to said **BEIJING VCORE TECHNOLOGY CO.,LTD.** as the assignee of the whole right, title, and interest thereto.

And we further agree to sign and properly execute such necessary and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and for obtaining any reissue or reissues of any Letters Patent which may be granted for our aforesaid invention, as the assignee thereof shall hereafter require and prepare at its own expense.

WITNESS, our signature and date of execution:

*Jiye Zhao*  
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Jiye ZHAO

2021.12.07  
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Date

*Dandan Huan*  
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Dandan HUAN

2021.12.7  
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Date

**PATENT**